



# PMEG3002EJ-Q

30 V, 200 mA low VF Schottky barrier rectifier

1 November 2023

Product data sheet

## 1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD323F (SC-90) small and flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Average forward current:  $I_{F(AV)} \leq 0.2$  A
- Reverse voltage:  $V_R \leq 30$  V
- Low forward voltage
- Small and flat lead SMD plastic package
- Qualified according to AEC-Q101 and recommended for use in automotive applications

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Ultra high-speed switching
- Low power consumption applications

## 4. Quick reference data

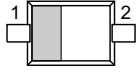

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20$ kHz; square wave; $T_{amb} \leq 135$ °C	-	-	0.2	A
		$\delta = 0.5$ ; $f = 20$ kHz; square wave; $T_{sp} \leq 145$ °C	-	-	0.2	A
$V_R$	reverse voltage	$T_j = 25$ °C	-	-	30	V
$V_F$	forward voltage	$I_F = 200$ mA; $T_j = 25$ °C	-	420	480	mV
$I_R$	reverse current	$V_R = 30$ V; $T_j = 25$ °C	-	10	40	$\mu$ A

[1] Device mounted on a ceramic Printed-Circuit Board (PCB),  $Al_2O_3$ , standard footprint.

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 SC-90 (SOD323F)	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
<a href="#">PMEG3002EJ-Q</a>	SC-90	plastic, surface-mounted package; 2 leads; 1.7 mm x 1.25 mm x 0.7 mm body	<a href="#">SOD323F</a>

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG3002EJ-Q	1M

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	$T_j = 25\text{ °C}$		-	30	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; square wave; $T_{amb} \leq 135\text{ °C}$	[1]	-	0.2	A
		$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; square wave; $T_{sp} \leq 145\text{ °C}$		-	0.2	A
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1\text{ ms}$ ; $\delta \leq 0.25$		-	2.6	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8\text{ ms}$ ; square wave; $T_j = 25\text{ °C}$ prior to surge; $T_{j(init)} = 25\text{ °C}$		-	2.75	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2] [3]	-	385	mW
			[2] [4]	-	695	mW
			[5] [2]	-	1.045	W
$T_j$	junction temperature			-	150	°C
$T_{amb}$	ambient temperature			-55	150	°C
$T_{stg}$	storage temperature			-65	150	°C

[1] Device mounted on a ceramic Printed-Circuit Board (PCB),  $Al_2O_3$ , standard footprint.

[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .

[5] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2] [3]	-	-	325	K/W
			[1] [2] [4]	-	-	180	K/W
			[1] [2] [5]	-	-	120	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6]	-	-	25	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.
- [2] Reflow soldering is the only recommended soldering method.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [5] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [6] Soldering point of cathode tab.

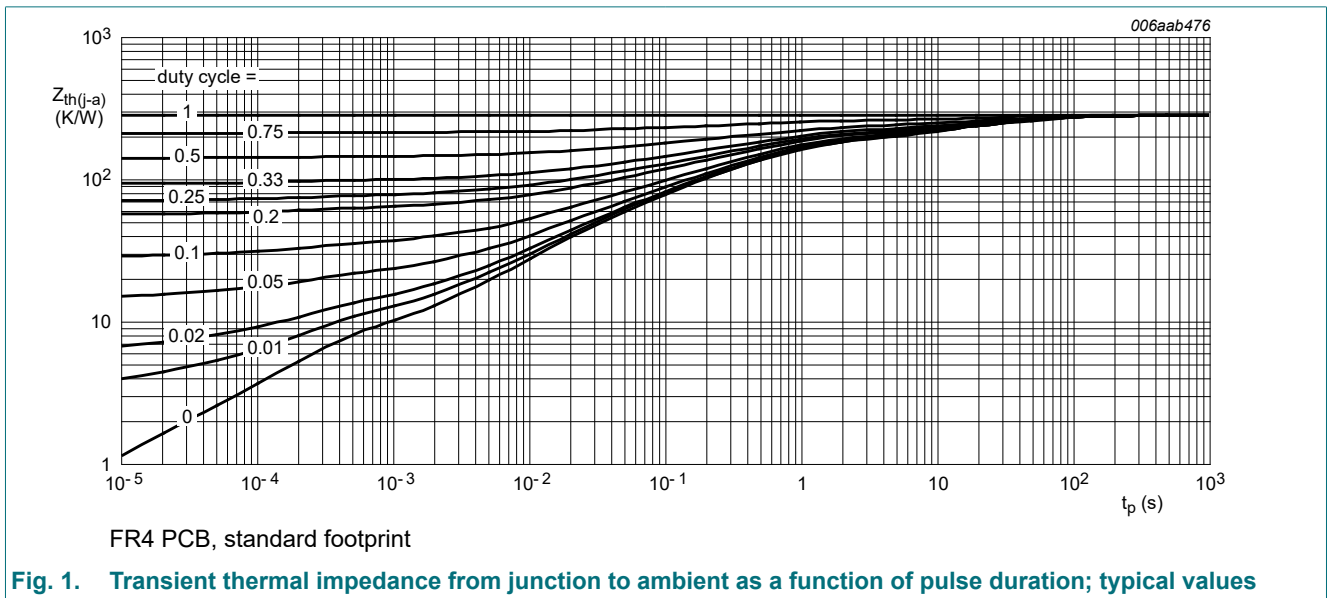


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

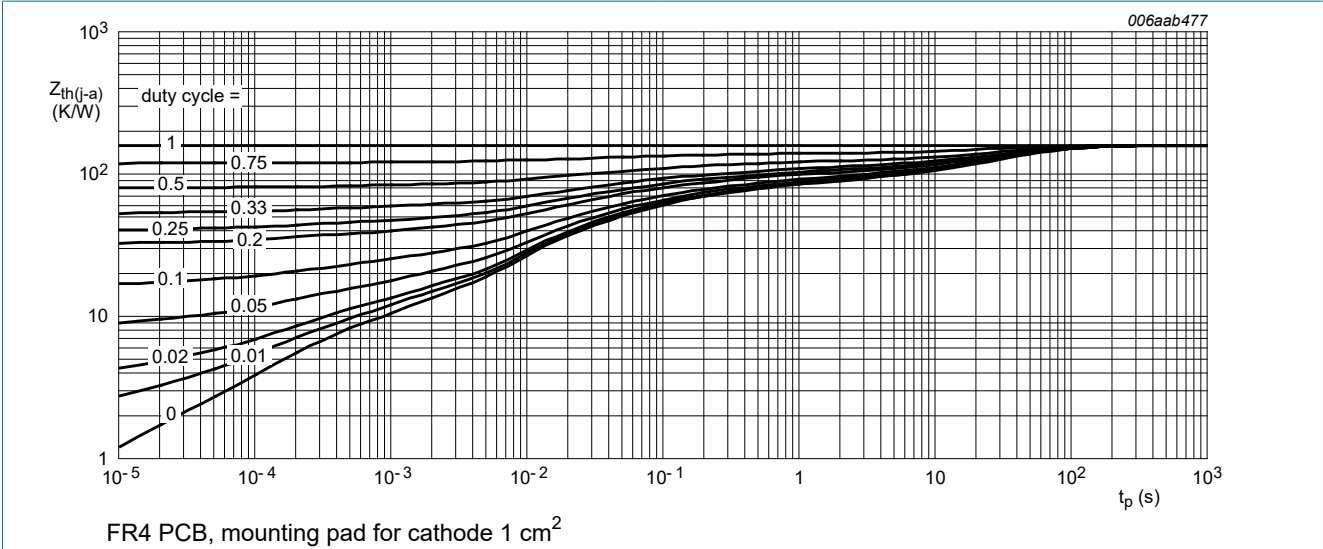


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

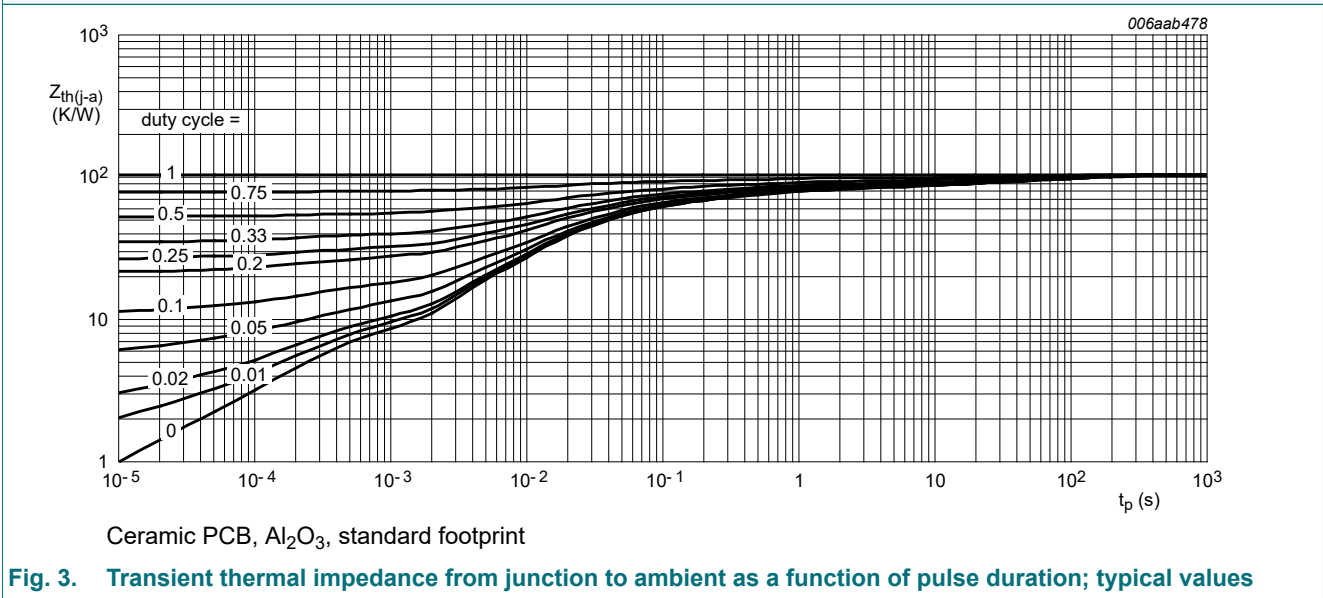
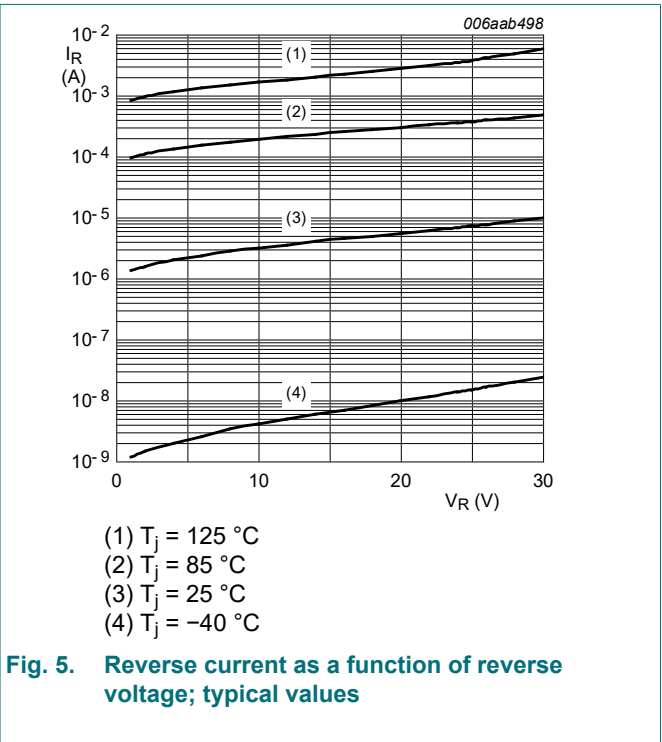
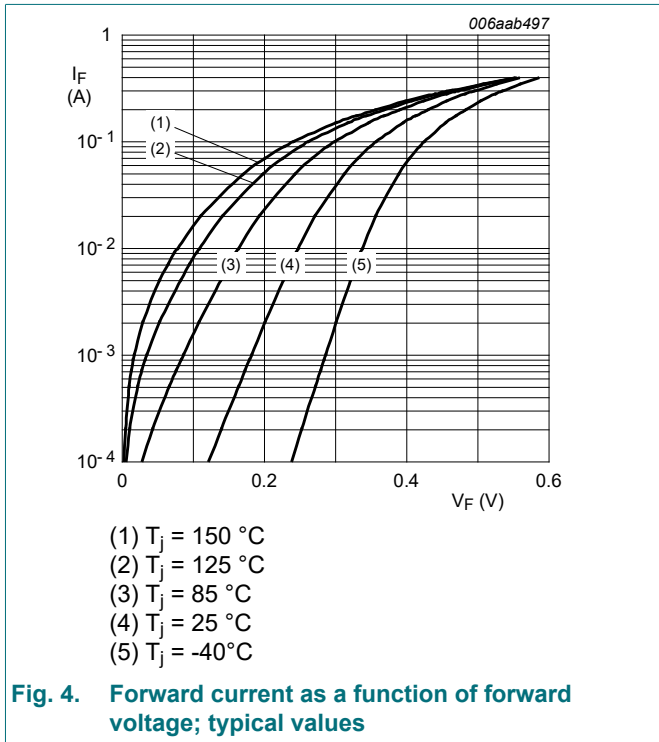


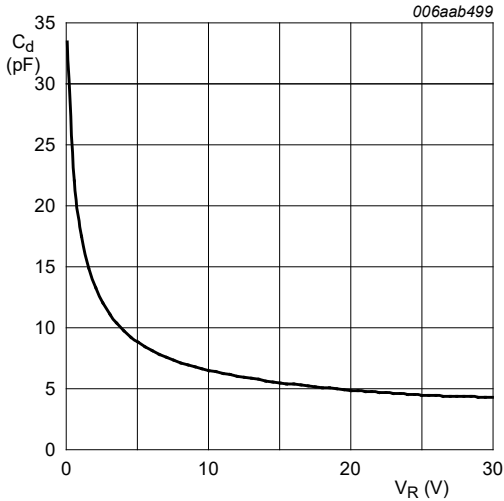
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

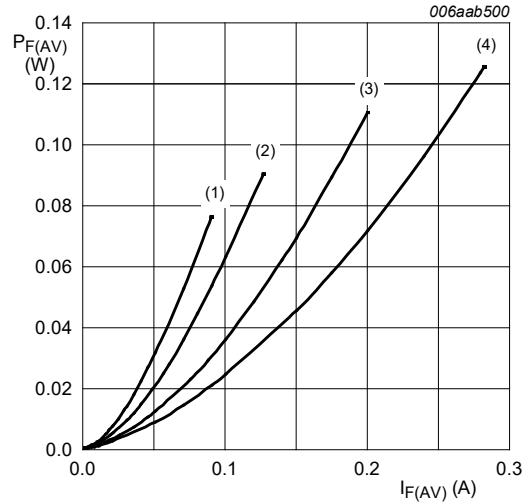
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage	$I_F = 0.1 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$	-	130	190	mV
		$I_F = 1 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$	-	190	250	mV
		$I_F = 10 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$	-	250	300	mV
		$I_F = 100 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$	-	355	400	mV
		$I_F = 200 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$	-	420	480	mV
$I_R$	reverse current	$V_R = 10 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	2.5	10	$\mu\text{A}$
		$V_R = 30 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	10	40	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$	-	18	-	pF
		$V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$	-	7	-	pF
$t_{rr}$	reverse recovery time	When switched from $I_F = 10 \text{ mA}$ to $I_R = 10 \text{ mA}; R_L = 100 \text{ } \Omega$ ; measured at $I_R = 1 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$	-	5	-	ns





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

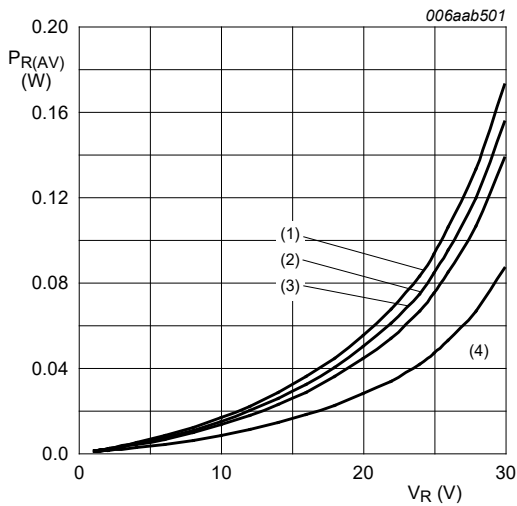
**Fig. 6. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 150 \text{ }^\circ\text{C}$

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

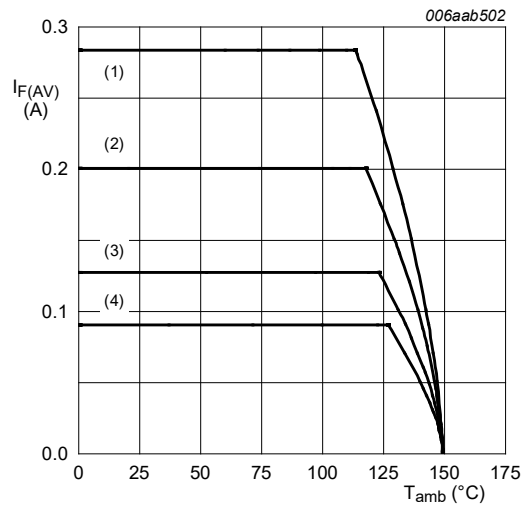
**Fig. 7. Average forward power dissipation as a function of average forward current; typical values**



$T_j = 125 \text{ }^\circ\text{C}$

- (1)  $\delta = 1$
- (2)  $\delta = 0.9$
- (3)  $\delta = 0.8$
- (4)  $\delta = 0.5$

**Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values**

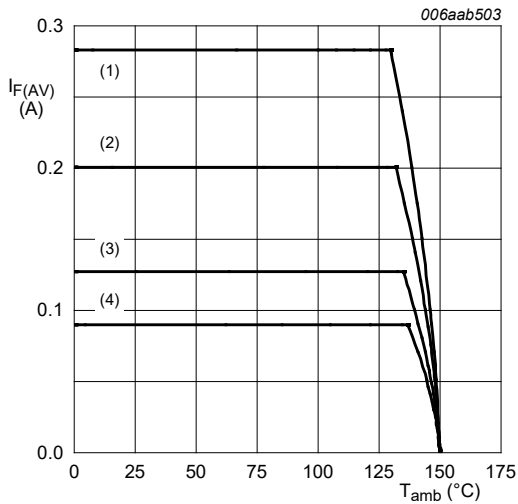


FR4 PCB, standard footprint

$T_j = 150 \text{ }^\circ\text{C}$

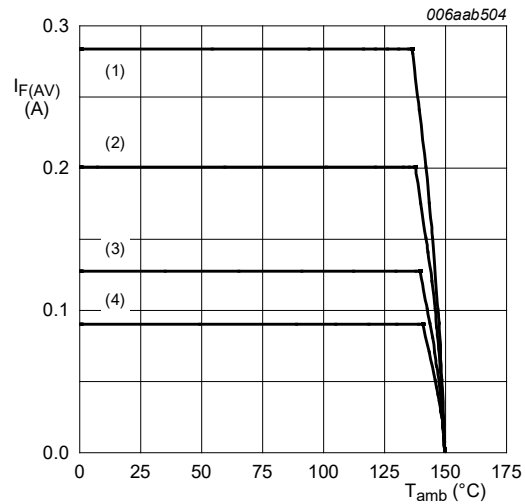
- (1)  $\delta = 1; \text{DC}$
- (2)  $\delta = 0.5; f = 20 \text{ kHz}$
- (3)  $\delta = 0.2; f = 20 \text{ kHz}$
- (4)  $\delta = 0.1; f = 20 \text{ kHz}$

**Fig. 9. Average forward current as a function of ambient temperature; typical values**



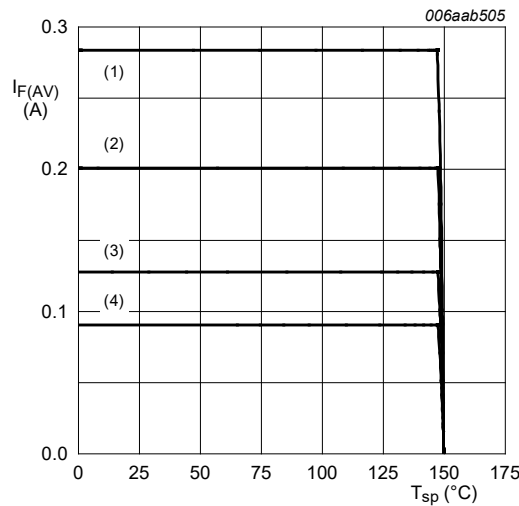
FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint  
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

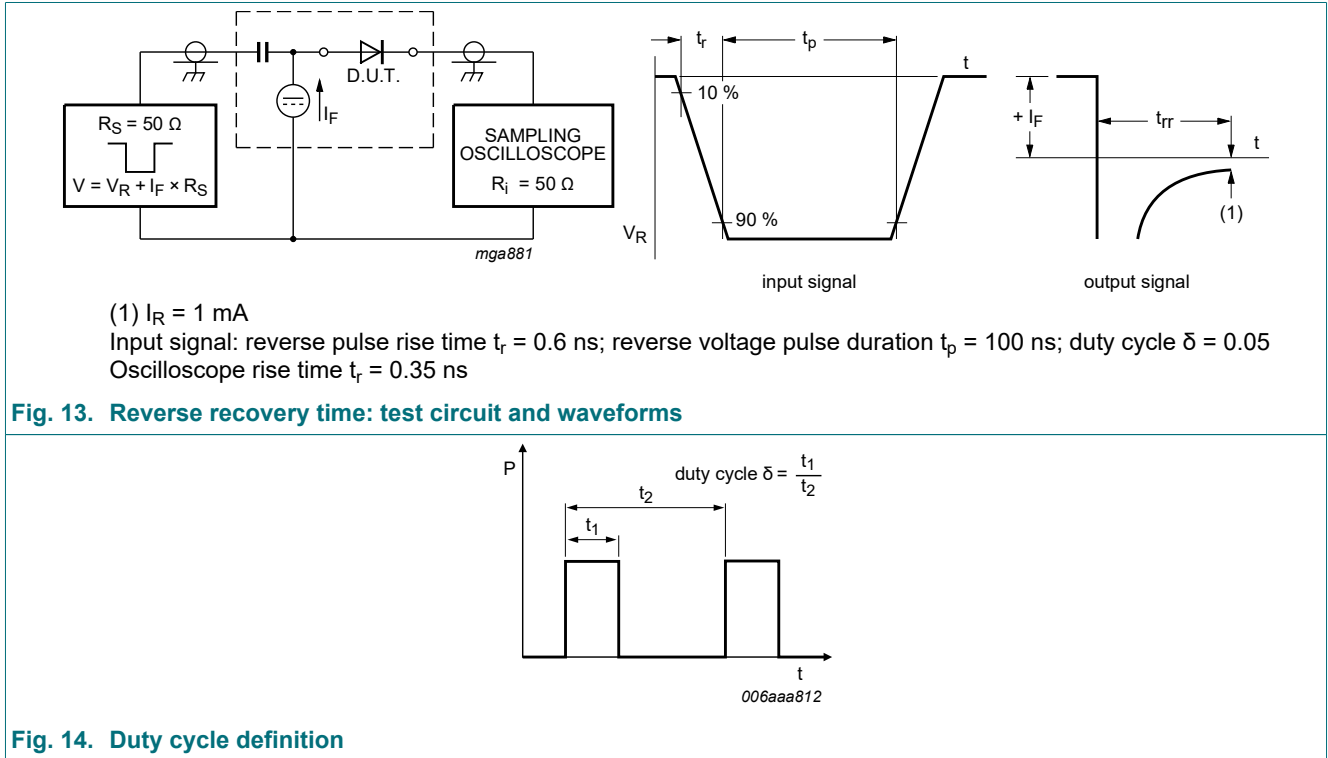
Fig. 11. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

Fig. 12. Average forward current as a function of solder point temperature; typical values

### 11. Test information



The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC}$$

$$I_{RMS} = I_M \times \sqrt{\delta} \text{ with } I_{RMS} \text{ defined as RMS current}$$

#### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.



## 12. Package outline

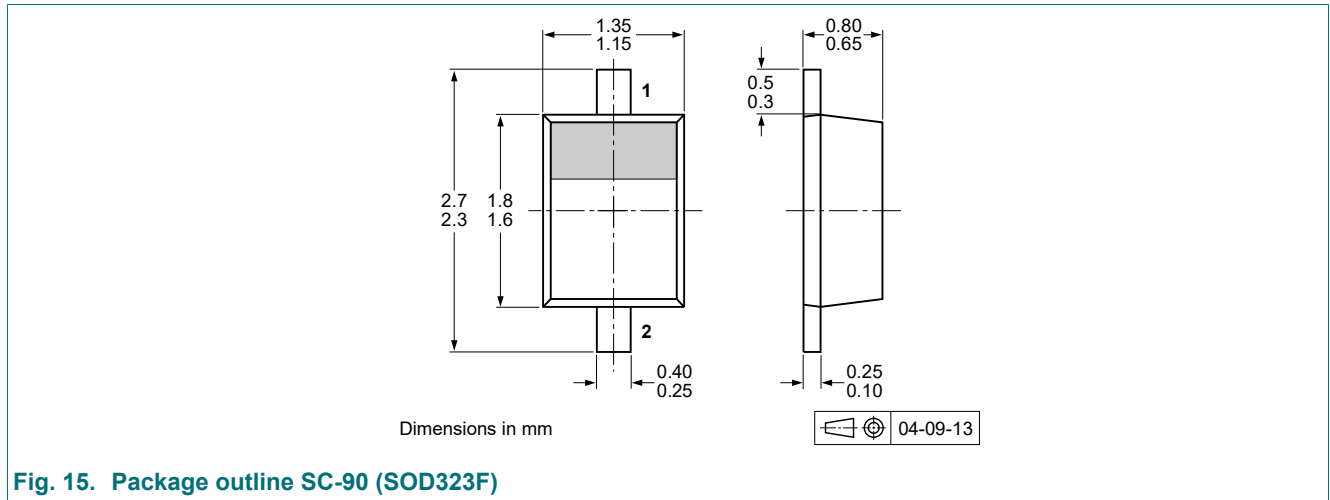


Fig. 15. Package outline SC-90 (SOD323F)

## 13. Soldering

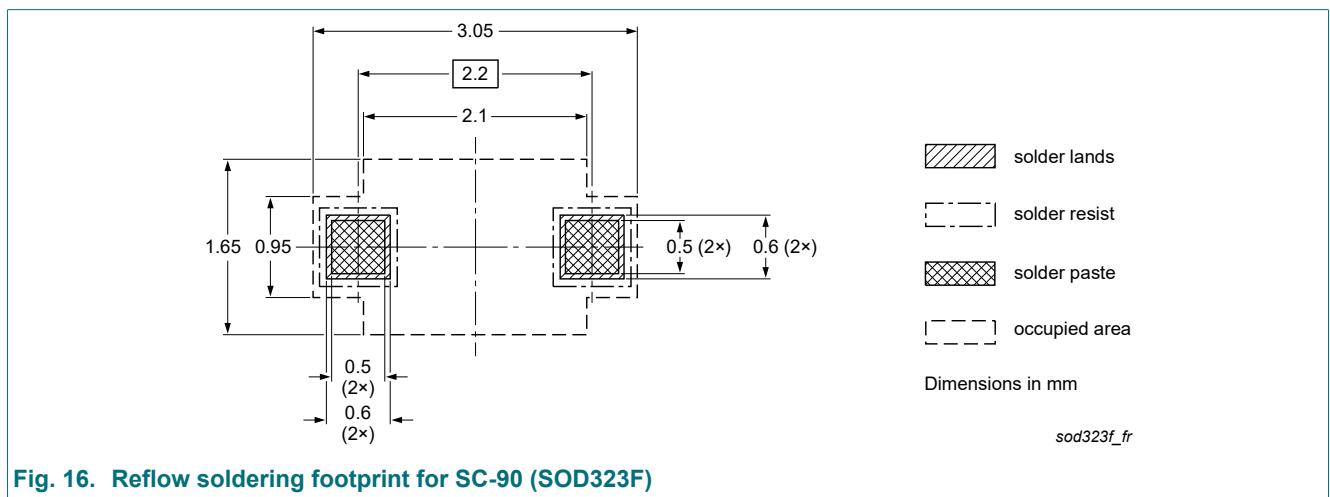


Fig. 16. Reflow soldering footprint for SC-90 (SOD323F)

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG3002EJ-Q v.1	20231101	Product data sheet	-	-

## 15. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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## Contents

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1. General description.....	1
2. Features and benefits.....	1
3. Applications.....	1
4. Quick reference data.....	1
5. Pinning information.....	2
6. Ordering information.....	2
7. Marking.....	2
8. Limiting values.....	2
9. Thermal characteristics.....	3
10. Characteristics.....	5
11. Test information.....	8
12. Package outline.....	9
13. Soldering.....	9
14. Revision history.....	10
15. Legal information.....	11

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